



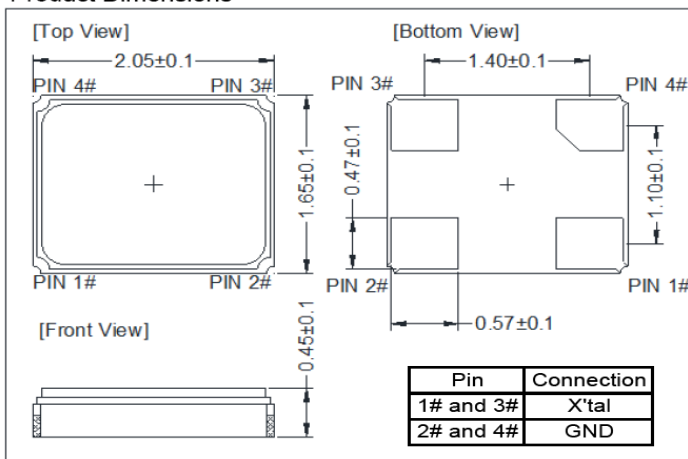
TYPICAL APPLICATION

- Bluetooth , Mobile phone, Wireless LAN.
- Office Automation
- Audio & Video

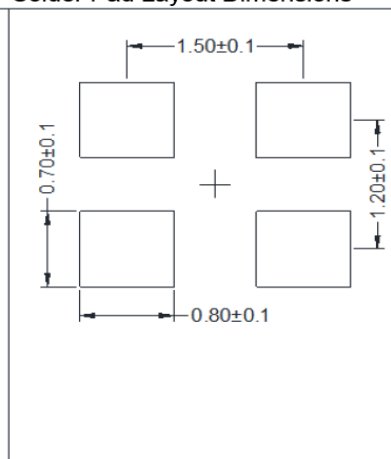


DIMENSIONS (mm)

Product Dimensions



Solder Pad Layout Dimensions



ELECTRICAL SPECIFICATION

PARAMETERS	XMF-SMD2016			UNITS	CONDITIONS
	MIN	TYP	MAX		
Nominal Frequency	16	-	52	MHz	-
Mode of vibration	Fundamental				-
Frequency Tolerance	10 20 30 or specify			ppm	@+25°C±3°C
Frequency Stability	Table 2			ppm	Ref 25°C±3°C
Load Capacitance	8pF 10pF or specify			pF	-
Shunt Capacitance	-	-	2	pF	@+25°C±3°C
Equivalent Series Resistance	Table 1			Ω	-
Drive Level		10	200	μW	-
Operating Temperature Range	-40	-	125	°C	-
Storage Temperature	-55	-	125	°C	-
Aging (First Year)	-3	-	3	ppm	-
Insulation Resistan	500	-	-	MΩ	@DC100V

EQUIVALENT SERIES RESISTANCE (Table 1)

Frequency Range	MODE	E.S.R.(Ω)
16MHz≤F0 < 20MHz	Fundamental	120
20MHz≤F0 ≤30MHz	Fundamental	80
30MHz < F0 ≤40MHz	Fundamental	60
40MHz < F0 ≤52MHz	Fundamental	50

FREQ. STABILITY vs. TEMP. RANGE(Table 2)

Temp.°C \ ppm	±10	±15	±20	±30	±50
-10 ~ 60	○	○	○	○	○
-20 ~ 70	○	○	○	○	○
-40 ~ 85	X	△	○	○	○
-40 ~ 105	X	X	△	○	○
-40 ~ 125	X	X	X	X	○

○: Available △:Conditional X: Not available